



30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| V _{(BR)DSS} | R _{DS(ON)} max | I _D max T _A = 25°C |
|----------------------|-------------------------------|---|
| 30V | 12mΩ @ V _{GS} = 10V | 10.3 A |
| 307 | 16mΩ @ V _{GS} = 4.5V | 9.3 A |

Description

This MOSFET has been designed to minimize the on-state resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Backlighting
- **Power Management Functions**
- **DC-DC Converters**

Features and Benefits

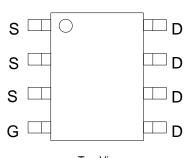
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 standards for High Reliability

Mechanical Data

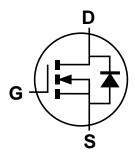
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.076 grams (approximate)







Top View Pin Configuration



Equivalent Circuit

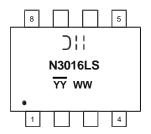
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|------|------------------|
| DMN3016LSS-13 | SO-8 | 2500/Tape & Reel |

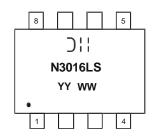
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain < 900ppm bromine, < 900ppm chlorine (< 1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Chengdu A/T Site



Shanghai A/T Site

);; = Manufacturer's Marking N3016LS = Product Type Marking Code YYWW = Date Code Marking YY or \overline{YY} = Year (ex: 14 = 2014)

WW = Week (01 - 53)

YY = Date Code Marking for SAT (Shanghai Assembly/ Test site) YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | | Symbol | Value | Units |
|--|-----------------|--|------------------|--------------|-------|
| Drain-Source Voltage | | | V _{DSS} | 30 | V |
| Gate-Source Voltage | | | V _{GSS} | ±20 | V |
| | Steady State | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | 10.3 8.3 | А |
| Continuous Drain Current (Note 6) V _{GS} = 10V | t<10s | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | 13.4 10.6 | А |
| Continuous Drain Current (Note 6) V _{GS} = 4.5V | Steady State | $T_A = +25$ °C $T_A = +70$ °C | I _D | 9.3 7.3 | А |
| | t<10s | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | 12.0 9.5 | А |
| Maximum Continuous Body Diode Forward Current (Note 6) | | | I _S | 2.5 | Α |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%) | | | I _{DM} | 80 | Α |
| Avalanche Current (Note 7) L = 0.1mH | | | I _{AS} | 22 | Α |
| Avalanche Energy (Note 7) L = 0.1mH | | | Eas | 25 | mJ |

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units | |
|--|-----------------------------------|-----------------|-------|------|
| Total Power Dissipation (Note 5) | P_D | 1.5 | W | |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | J | 82 | °C/W |
| Thermal Resistance, Junction to Ambient (Note 5) | t<10s | $R_{\theta JA}$ | 48 | °C/W |
| Total Power Dissipation (Note 6) | | P_{D} | 2.0 | W |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State | 5 | 60 | °C/W |
| Thermal Resistance, Junction to Ambient (Note 6) | t<10s | $R_{\theta JA}$ | 37 | °C/W |
| Thermal Resistance, Junction to Case | | $R_{	heta JC}$ | 6.4 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to 150 | °C | |

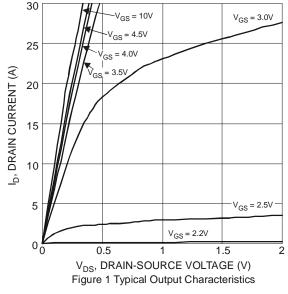
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

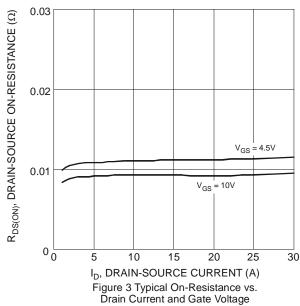
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|---------------------|-----|------|------|-------|--|--|
| OFF CHARACTERISTICS (Note 8) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 30 | _ | _ | V | $V_{GS} = 0V, I_D = 250\mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | 1 | μΑ | $V_{DS} = 30V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 8) | • | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | 1.3 | _ | 2.5 | V | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | |
| Static Drain-Source On-Resistance | | _ | 8 | 12 | 0 | $V_{GS} = 10V, I_D = 12A$ | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 12 | 16 | mΩ | $V_{GS} = 4.5V, I_D = 10A$ | |
| Diode Forward Voltage | V _{SD} | _ | 0.7 | 1.0 | V | $V_{GS} = 0V, I_{S} = 1A$ | |
| DYNAMIC CHARACTERISTICS (Note 9) | | | | | | • | |
| Input Capacitance | C _{iss} | _ | 1415 | _ | | V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz | |
| Output Capacitance | Coss | _ | 119 | _ | pF | | |
| Reverse Transfer Capacitance | C _{rss} | _ | 82 | _ | | | |
| Gate resistance | Rg | _ | 2.6 | 3.2 | Ω | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$ | |
| Total Gate Charge (V _{GS} = 4.5V) | Qg | _ | 11.3 | _ | | V _{DS} = 15V, I _D = 12A | |
| Total Gate Charge (V _{GS} = 10V) | Qq | _ | 25.1 | _ | nC | | |
| Gate-Source Charge | Q _{gs} | _ | 3.5 | _ | i iiC | | |
| Gate-Drain Charge | Q _{gd} | _ | 3.6 | _ | | | |
| Turn-On Delay Time | t _{D(on)} | _ | 4.8 | _ | | $V_{DD} = 15V, V_{GS} = 10V,$ $R_{L} = 1.25\Omega, R_{G} = 3\Omega,$ | |
| Turn-On Rise Time | t _r | _ | 16.5 | | | | |
| Turn-Off Delay Time | t _{D(off)} | _ | 26.1 | _ | ns | | |
| Turn-Off Fall Time | t _f | | 5.6 | _ | 1 | | |
| Reverse Recovery Time | T _{rr} | _ | 8.5 | _ | ns | 1 101 11/1 5001/ | |
| Reverse Recovery Charge | Qrr | _ | 7.0 | _ | nC | $I_F = 12A$, di/dt = 500A/ μ s | |

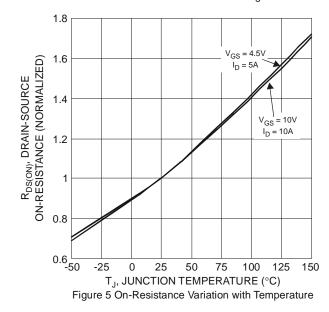
Notes:

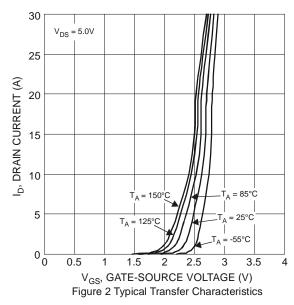
- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. UIS in production with L = 0.1mH, starting $T_A = +25$ °C.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.

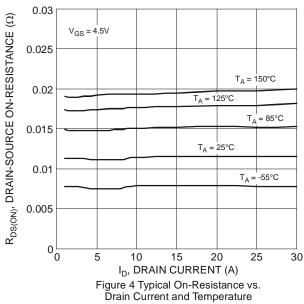


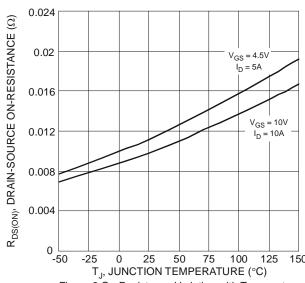














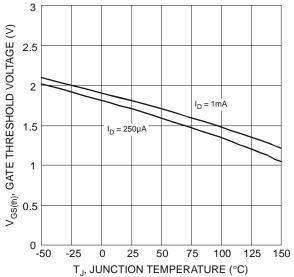


Figure 7 Gate Threshold Variation vs. Ambient Temperature

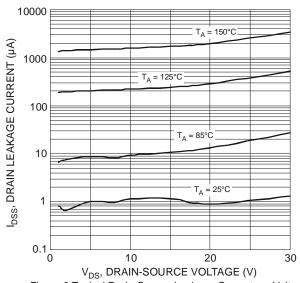
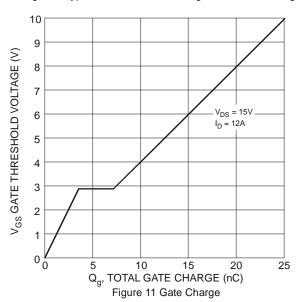
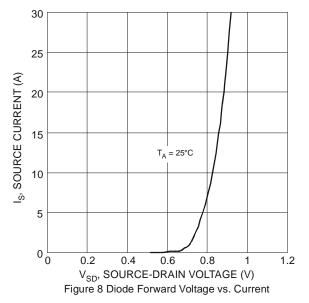
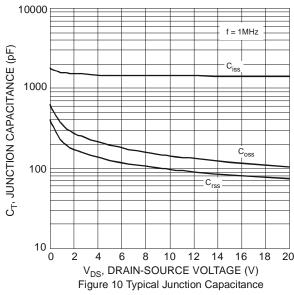


Figure 9 Typical Drain-Source Leakage Current vs. Voltage







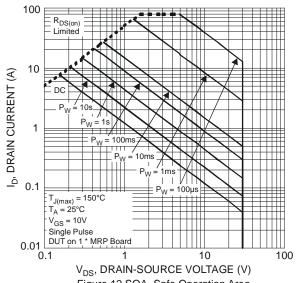
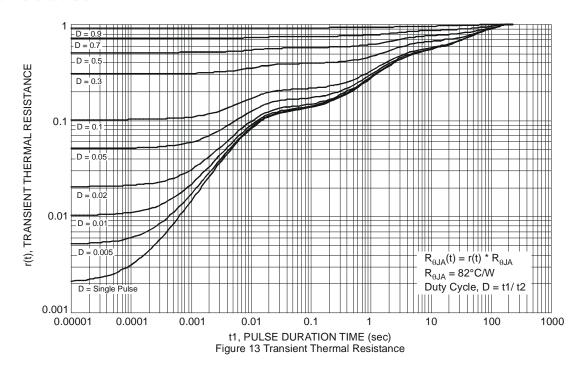


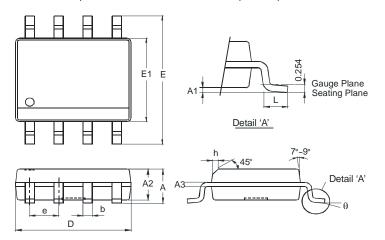
Figure 12 SOA, Safe Operation Area





Package Outline Dimensions

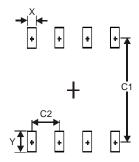
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



| SO-8 | | | | | |
|----------------------|-----------|------|--|--|--|
| Dim | Min | Max | | | |
| Α | - | 1.75 | | | |
| A 1 | 0.10 | 0.20 | | | |
| A2 | 1.30 | 1.50 | | | |
| А3 | 0.15 | 0.25 | | | |
| b | 0.3 | 0.5 | | | |
| D | 4.85 | 4.95 | | | |
| Е | 5.90 | 6.10 | | | |
| E1 | 3.85 3.95 | | | | |
| е | 1.27 Typ | | | | |
| h | - | 0.35 | | | |
| L | 0.62 | 0.82 | | | |
| θ | 0° | 8° | | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Х | 0.60 |
| Y | 1.55 |
| C1 | 5.4 |
| C2 | 1.27 |



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